

| | |
|--------------------|------|
| V_{DSS} | 45V |
| $R_{DS(on)(Max.)}$ | 67mΩ |
| I_D | ±3A |
| P_D | 1.0W |

●Features

- 1) Low on-resistance
- 2) Built-in G-S protection diode
- 3) Small surface mount package(TSMT3)

●Application

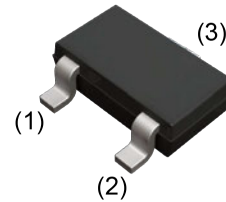
Switching

●Outline

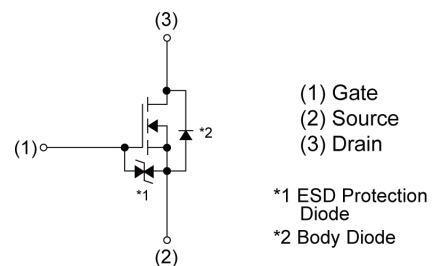
SOT-346T

SC-96

TSMT3



●Inner circuit



●Packaging specifications

| Type | Packing | Embossed Tape |
|---------------------------|----------------|---------------|
| | Reel size (mm) | 180 |
| Tape width (mm) | 8 | |
| Basic ordering unit (pcs) | 3000 | |
| Taping code | TL | |
| Marking | PV | |

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|---------------|-------------|------|
| Drain - Source voltage | V_{DSS} | 45 | V |
| Continuous drain current | I_D | ±3 | A |
| Pulsed drain current | I_{DP}^{*1} | ±12 | A |
| Gate - Source voltage | V_{GSS} | ±12 | V |
| Power dissipation | P_D^{*2} | 1.0 | W |
| | P_D^{*3} | 0.76 | W |
| Junction temperature | T_j | 150 | °C |
| Operating junction and storage temperature range | T_{stg} | -55 to +150 | °C |

● Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|--|-----------------|--------|------|------|------|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - ambient | R_{thJA}^{*2} | - | - | 125 | °C/W |
| | R_{thJA}^{*3} | - | - | 165 | °C/W |

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|--|---|---|--------|------|----------|---------------|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 1mA$ | 45 | - | - | V |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$ | $I_D = 1mA$ referenced to 25°C | - | 46.8 | - | mV/°C |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 45V, V_{GS} = 0V$ | - | - | 1 | μA |
| Gate - Source leakage current | I_{GSS} | $V_{GS} = \pm 12V, V_{DS} = 0V$ | - | - | ± 10 | μA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = 10V, I_D = 1mA$ | 0.5 | - | 1.5 | V |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | $I_D = 1mA$ referenced to 25°C | - | -3.9 | - | mV/°C |
| Static drain - source on - state resistance | $R_{DS(on)}^{*4}$ | $V_{GS} = 4.5V, I_D = 3A$ | - | 48 | 67 | m Ω |
| | | $V_{GS} = 4V, I_D = 3A$ | - | 53 | 74 | |
| | | $V_{GS} = 2.5V, I_D = 3A$ | - | 68 | 95 | |
| Gate resistance | R_G | $f = 1MHz, \text{open drain}$ | - | 6.7 | - | Ω |
| Forward Transfer Admittance | $ Y_{fs} ^{*4}$ | $V_{DS} = 10V, I_D = 3A$ | 2.8 | - | - | S |

*1 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*2 Mounted on a ceramic board (30x30x0.8mm)

*3 Mounted on a FR4 (25x25x0.8mm)

*4 Pulsed

●Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|------------------------------|-------------------|-------------------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Input capacitance | C_{iss} | $V_{GS} = 0V$ | - | 510 | - | pF |
| Output capacitance | C_{oss} | $V_{DS} = 10V$ | - | 110 | - | |
| Reverse transfer capacitance | C_{rss} | $f = 1\text{MHz}$ | - | 55 | - | |
| Turn - on delay time | $t_{d(on)}^{*4}$ | $V_{DD} \approx 25V, V_{GS} = 4.5V$ | - | 12 | - | ns |
| Rise time | t_r^{*4} | $I_D = 1.5A$ | - | 19 | - | |
| Turn - off delay time | $t_{d(off)}^{*4}$ | $R_L \approx 16.6\Omega$ | - | 34 | - | |
| Fall time | t_f^{*4} | $R_G = 10\Omega$ | - | 26 | - | |

●Gate charge characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------|---------------|-----------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Total gate charge | Q_g^{*4} | $V_{DD} \approx 25V,$ | - | 6.2 | - | nC |
| Gate - Source charge | Q_{gs}^{*4} | $I_D = 3A,$ | - | 1.6 | - | |
| Gate - Drain charge | Q_{gd}^{*4} | $V_{GS} = 4.5V$ | - | 1.4 | - | |

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------------|---------------|--------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Continuous forward current | I_S | $T_a = 25^\circ\text{C}$ | - | - | 0.8 | A |
| Pulse forward current | I_{SP}^{*1} | | - | - | 12 | A |
| Forward voltage | V_{SD}^{*4} | $V_{GS} = 0V, I_S = 3A$ | - | - | 1.2 | V |

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

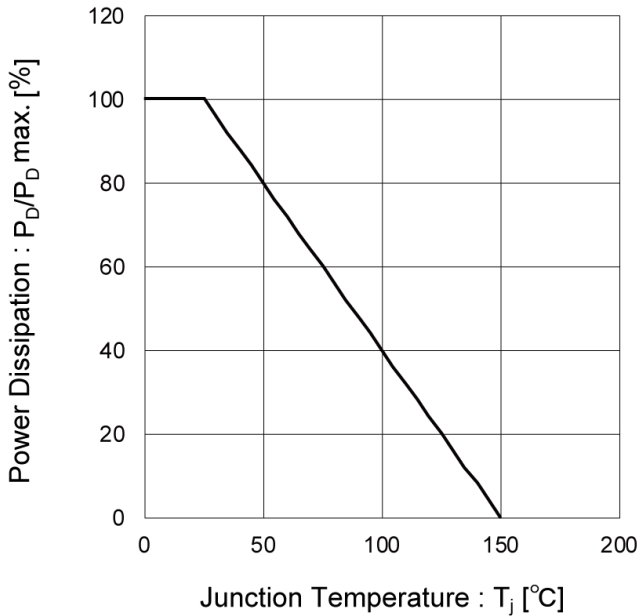


Fig.2 Maximum Safe Operating Area

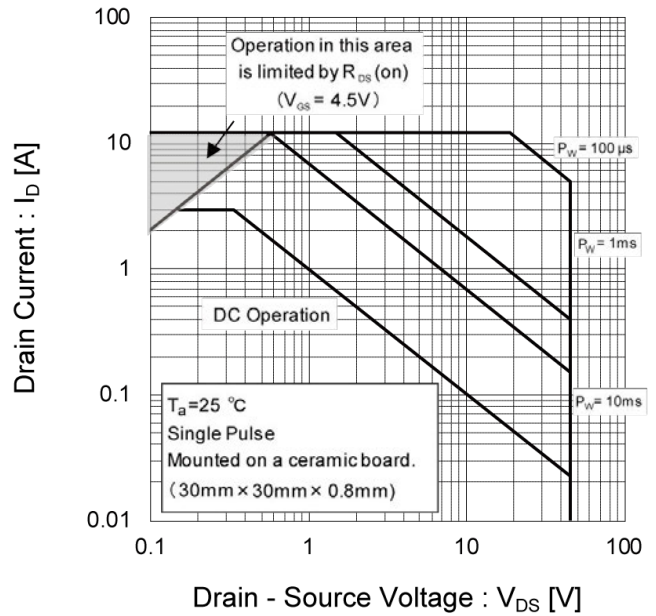


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

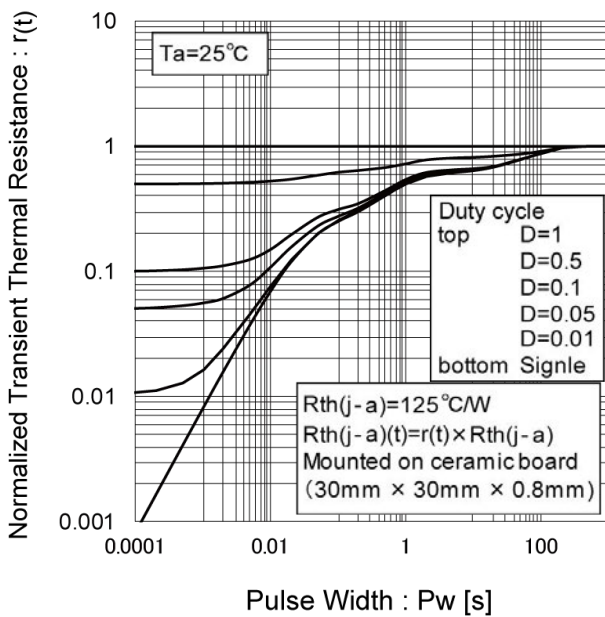
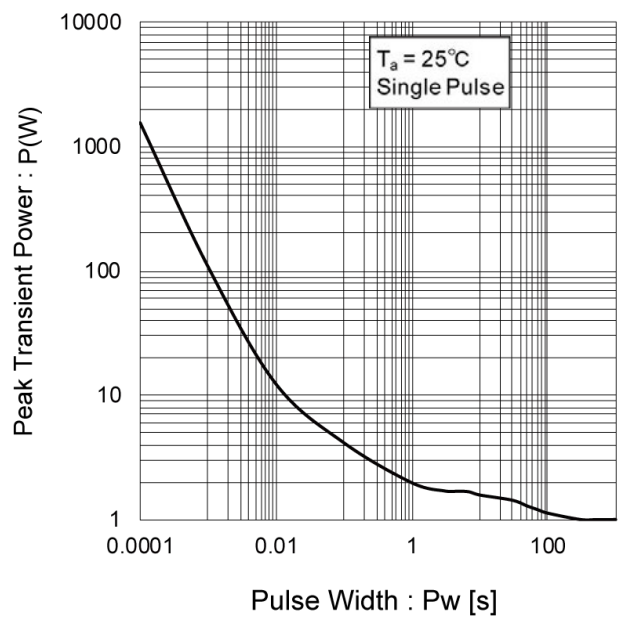


Fig.4 Single Pulse Maximum Power dissipation



● Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

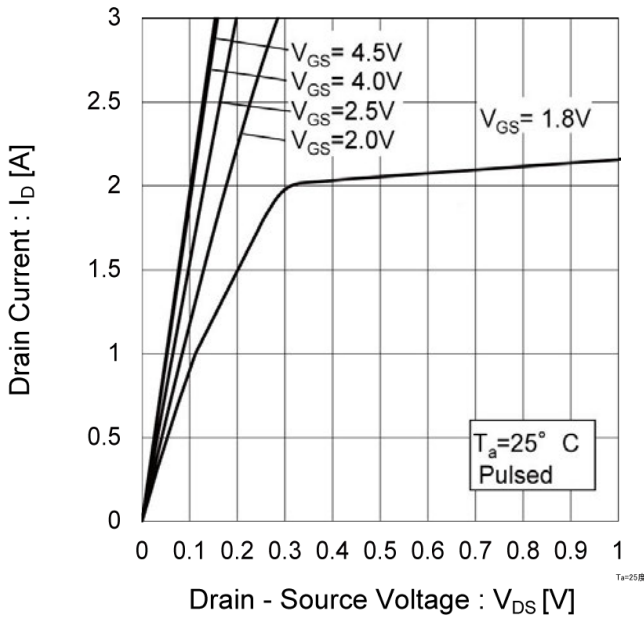


Fig.6 Typical Output Characteristics(II)

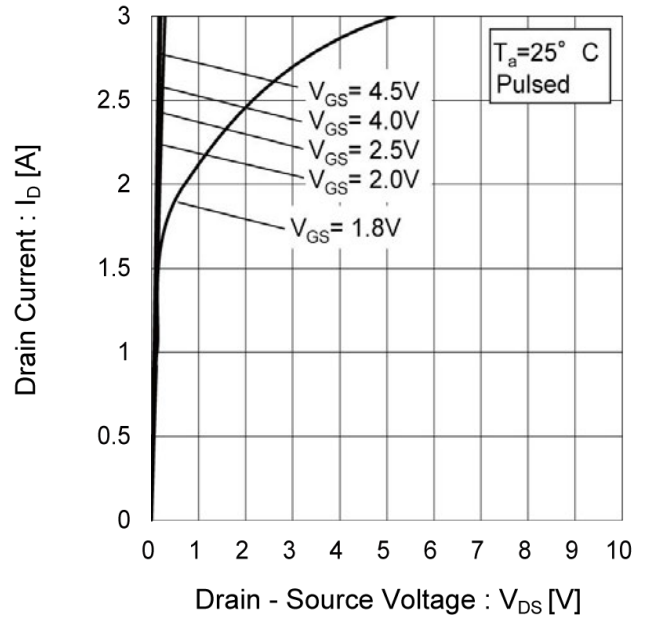


Fig.7 Breakdown Voltage vs. Junction Temperature

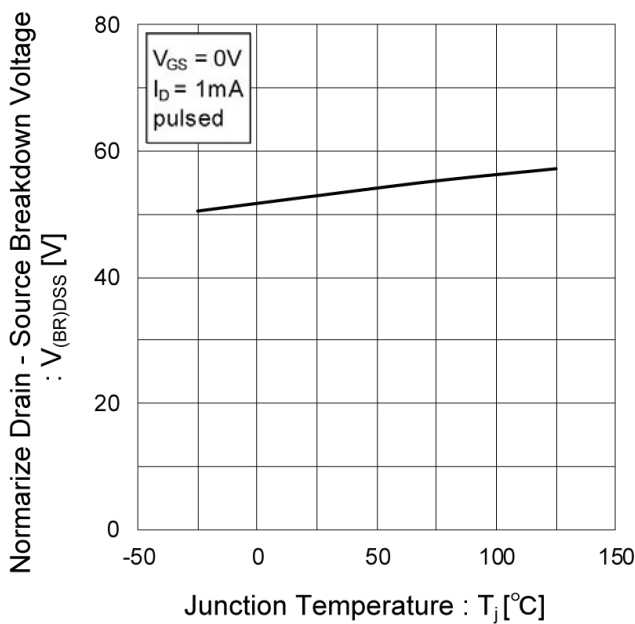
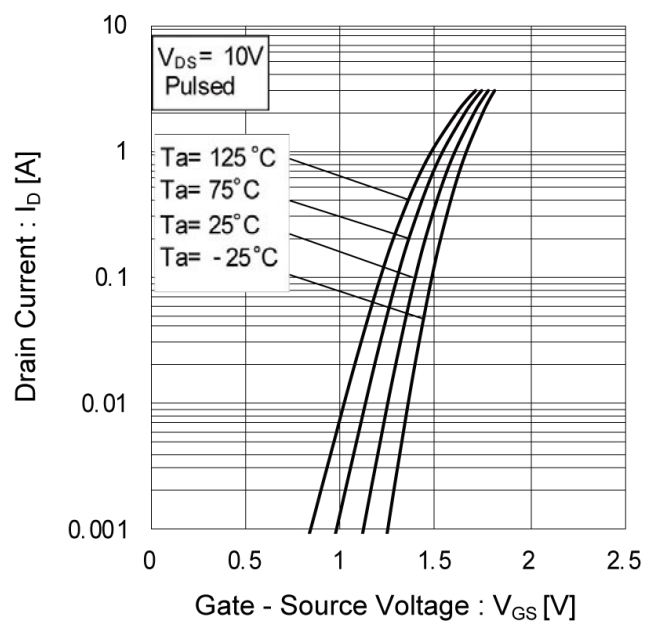


Fig.8 Typical Transfer Characteristics



● Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

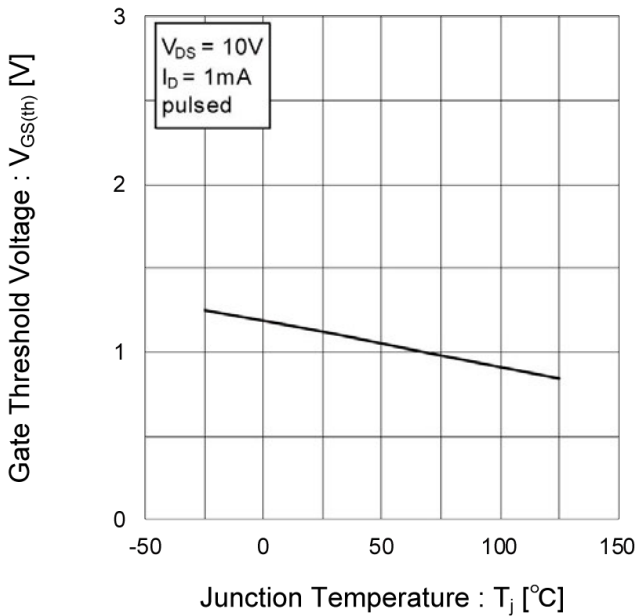


Fig.10 Forward Transfer Admittance vs. Drain Current

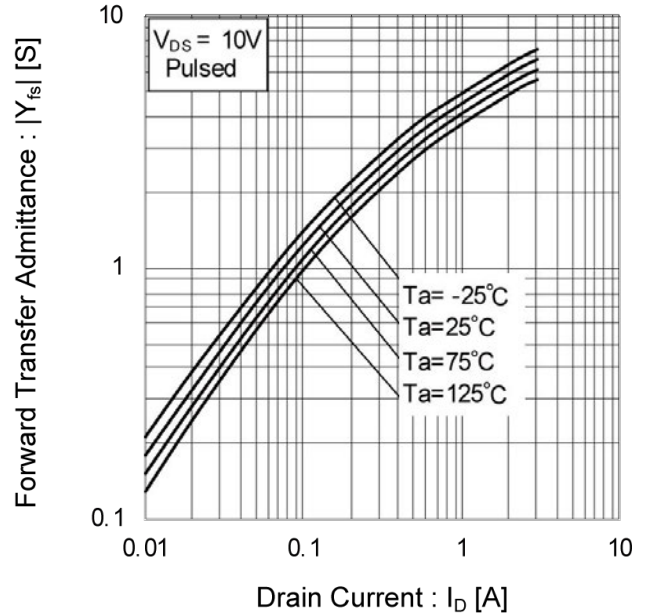


Fig.11 Drain Current Derating Curve

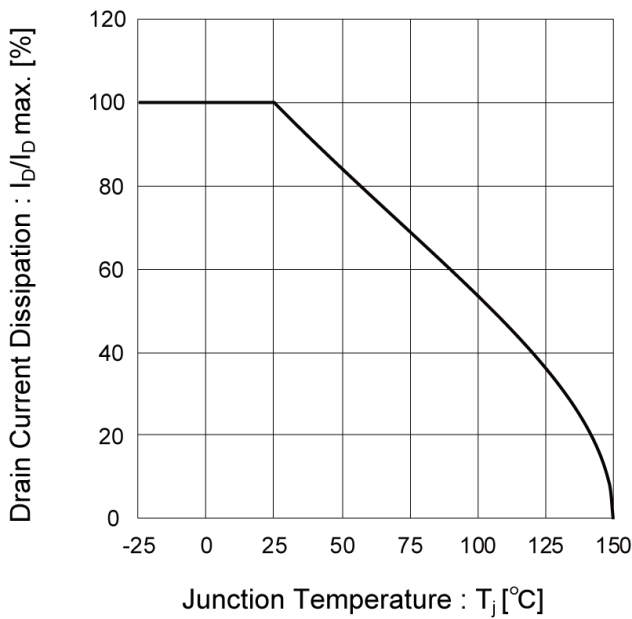
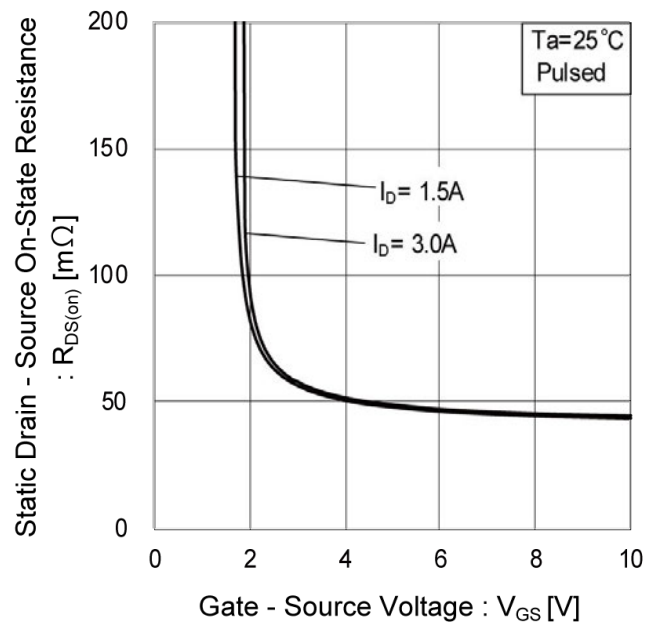


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

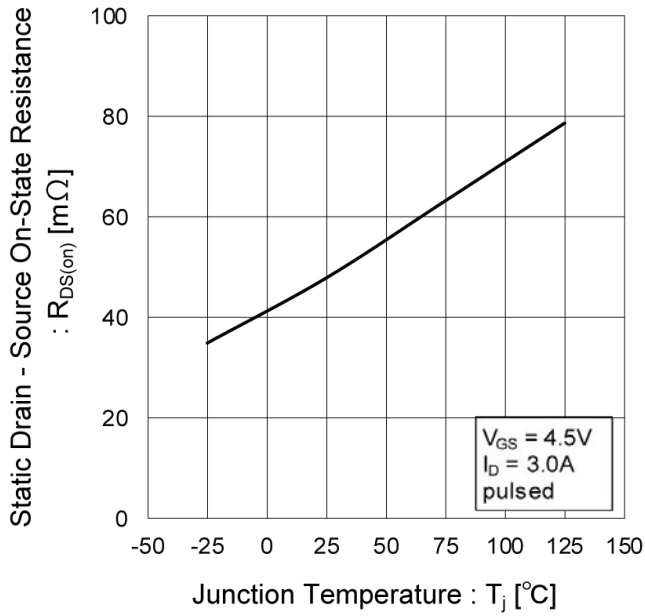
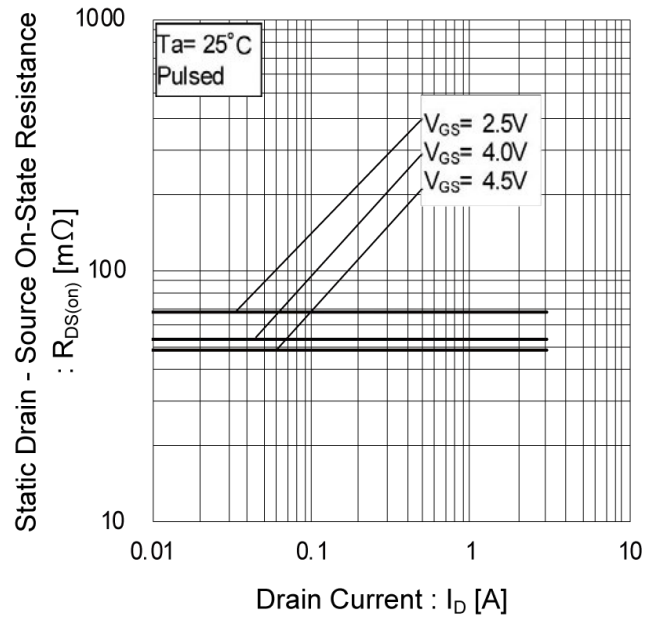


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)



● Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

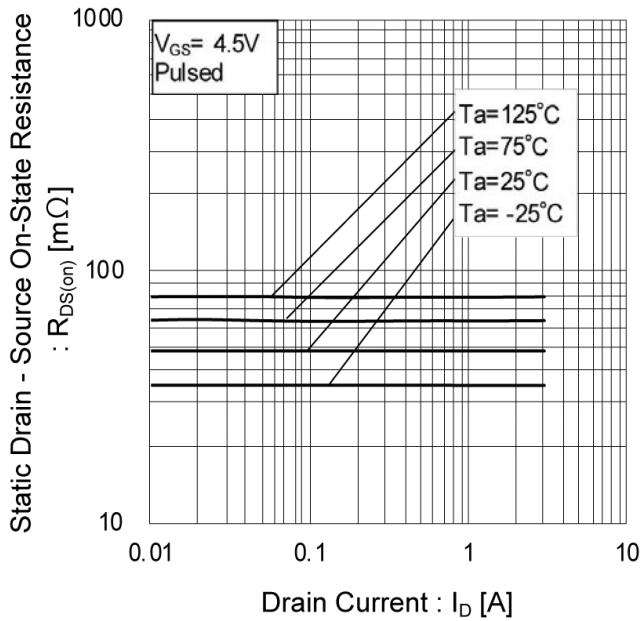


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

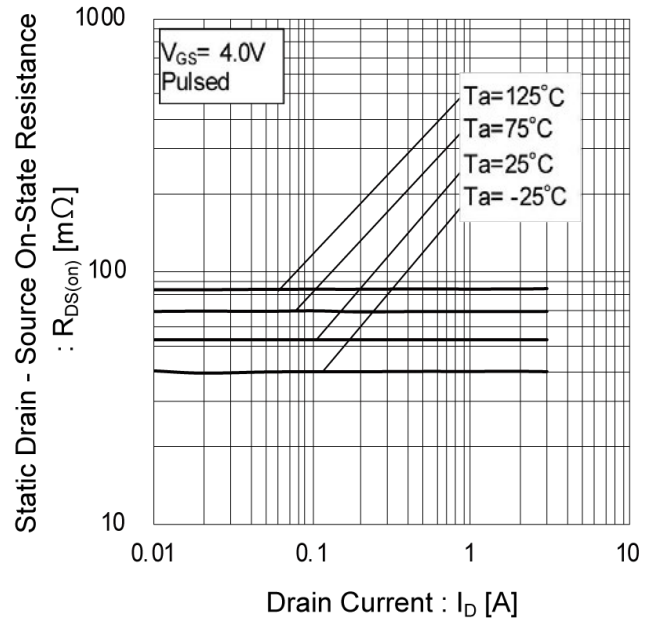
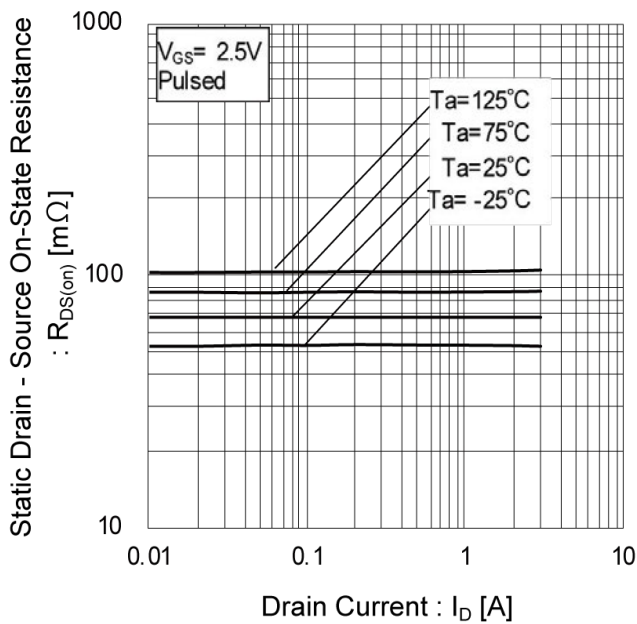


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)



● Electrical characteristic curves

Fig.18 Typical Capacitance vs. Drain - Source Voltage

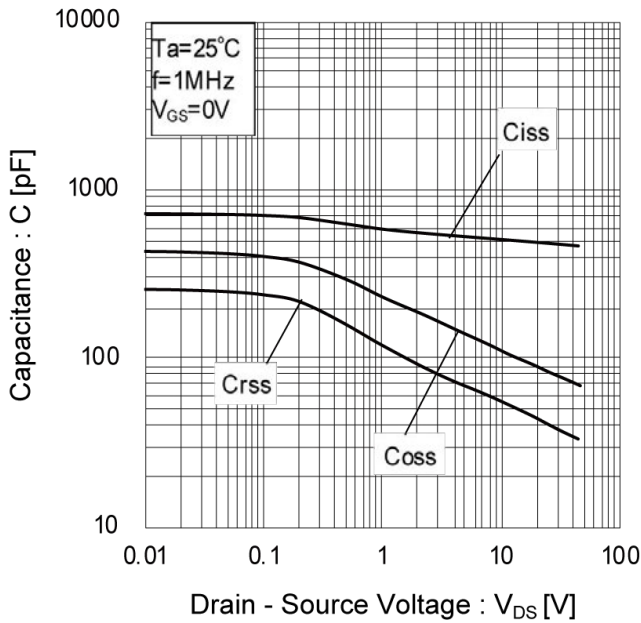


Fig.19 Switching Characteristics

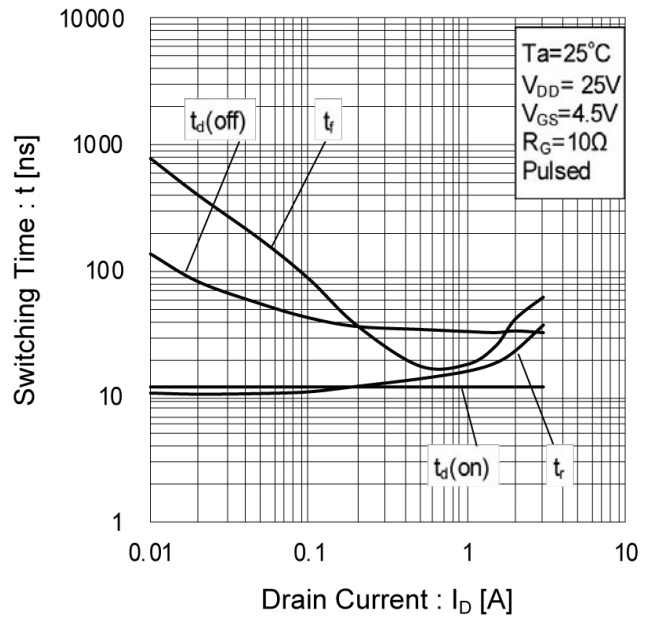


Fig.20 Dynamic Input Characteristics

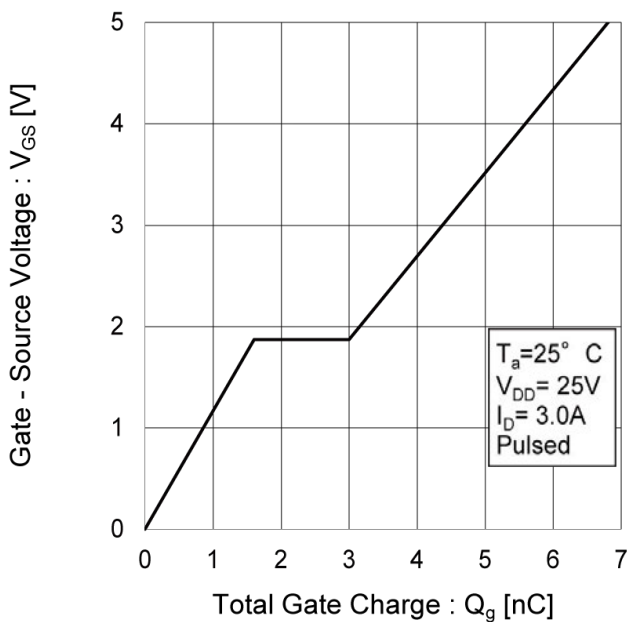
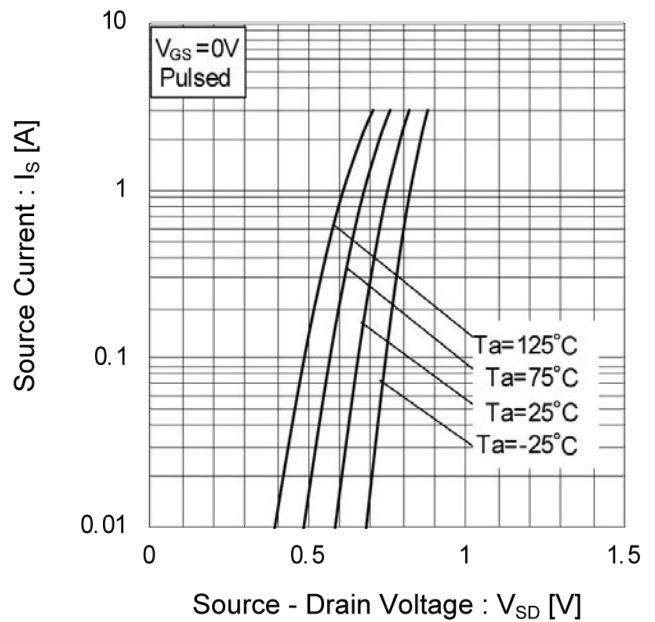


Fig.21 Source Current vs. Source Drain Voltage



● Measurement circuits

Fig. 1-1 SWITCHING TIME MEASUREMENT CIRCUIT

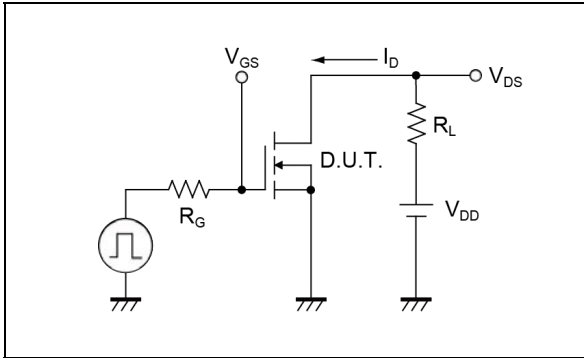


Fig. 1-2 SWITCHING WAVEFORMS

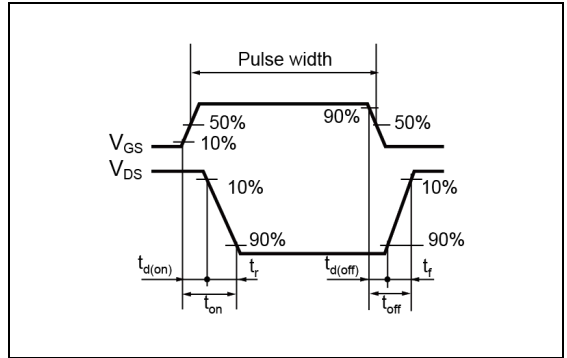


Fig. 2-1 GATE CHARGE MEASUREMENT CIRCUIT

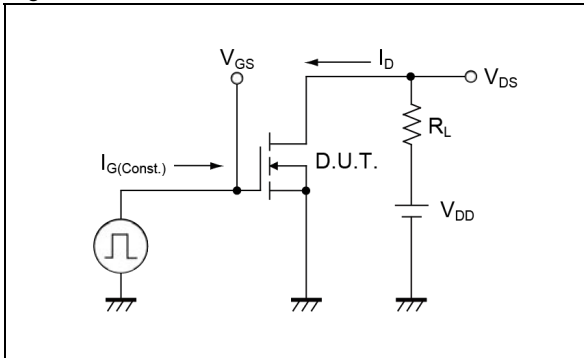
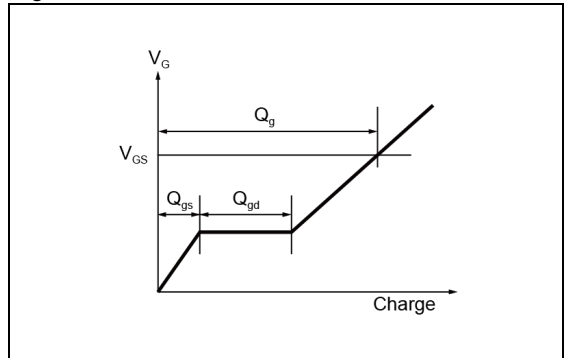
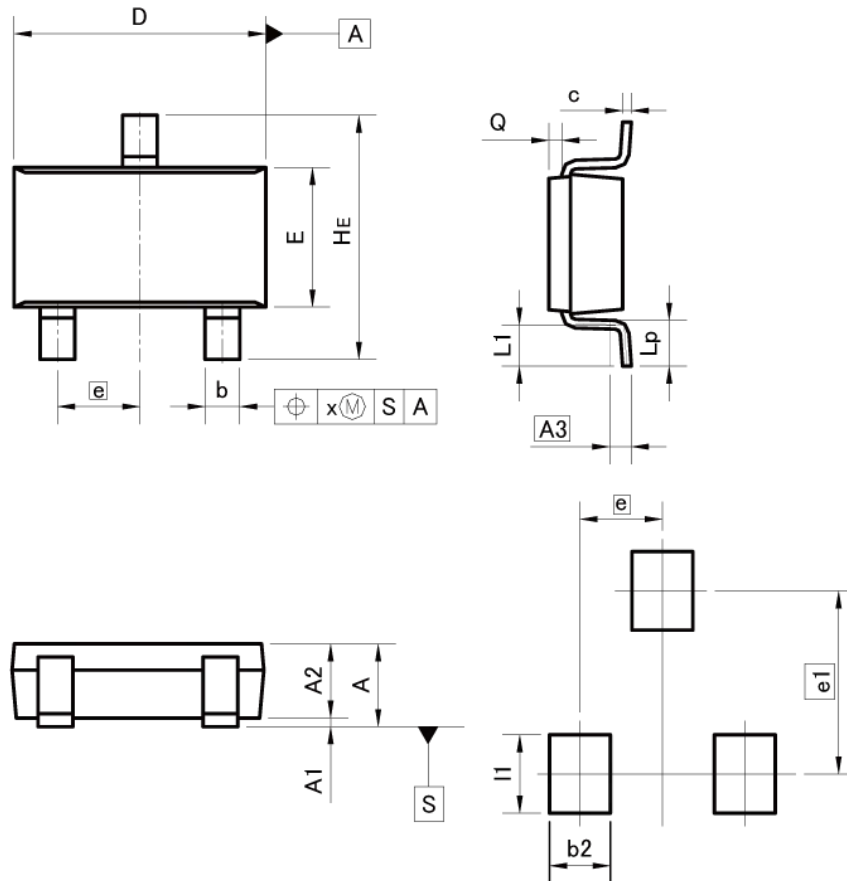


Fig. 2-2 GATE CHARGE WAVEFORM



●Dimensions

SOT-346T
SC-96
(TSMT3)



| DIM | MILIMETERS | | INCHES | |
|-----|------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | - | 1.00 | - | 0.039 |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 |
| A2 | 0.75 | 0.95 | 0.030 | 0.037 |
| A3 | 0.25 | | 0.010 | |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.10 | 0.26 | 0.004 | 0.010 |
| D | 2.80 | 3.00 | 0.110 | 0.118 |
| E | 1.50 | 1.80 | 0.059 | 0.071 |
| e | 0.95 | | 0.037 | |
| HE | 2.60 | 3.00 | 0.102 | 0.118 |
| L1 | 0.30 | 0.60 | 0.012 | 0.024 |
| Lp | 0.40 | 0.70 | 0.016 | 0.028 |
| Q | 0.05 | 0.25 | 0.002 | 0.010 |
| x | - | 0.20 | - | 0.008 |

| DIM | MILIMETERS | | INCHES | |
|-----|------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| b2 | - | 0.70 | - | 0.028 |
| e1 | 2.10 | | 0.083 | |
| l1 | - | 0.90 | - | 0.035 |

Dimension in mm/inches

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|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
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 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
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- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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